Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.   **(Currently Amended)** Method for transporting and inspecting semiconductor substrates, comprising the steps of:

providing at least three workstations and a changer arranged in a housing, ~~to be~~ the workstations and the changer all being open to each other in such a way that each of the workstations can be supplied with a semiconductor substrate;

lifting the changer and carrying out a rotational movement by a specific angular amount, in order to transfer at least one of the semiconductor substrates to another workstation;

lowering the changer and carrying out a rotational movement by the same angular amount in the opposite direction, without a semiconductor substrate resting on the changer; and

picking up a new semiconductor substrate from a substrate feed module.

Claim 2   **(Cancelled)**

3.   **(Original)** Method according to Claim 1, wherein the first workstation defines a transfer position, at which the semiconductor substrates are transferred from a substrate feed module into the housing or are transported back from the housing into the substrate feed module.

Claims 4-19   **(Cancelled)**

20.   **(Previously Presented)** An arrangement for transporting and inspecting semiconductor substrates, comprising:

at least three workstations arranged in a housing; and

a changer arranged in the same housing and at least three workstations being open to each other such that each of said workstations can be supplied with a semiconductor substrate;

said changer being rotatable by a specific angular amount in order to transfer at least one of the semiconductor substrates from one of said workstations to another of said workstations;

said changer being further rotatable by said specific angular amount in an opposite direction without transporting a semiconductor substrate in order to pick up a new semiconductor substrate from a substrate feed module.